

REMARKS/ARGUMENTS

Favorable reconsideration of this application, as presently amended and in view of the following discussion, is respectfully requested.

Claims 8-14 are pending. Claims 8 and 11 are presently amended.

First, applicant wishes to thank the examiner for the courtesies extended during the personal interview of December 16, 2003. During the interview, the outstanding office action was discussed and arguments in support of patentability were presented. However, no agreement was reached with regard to the ultimate patentability of all claims in the application, pending the examiner's further reconsideration and/or search. The comments below summarize the remarks made during the personal interview.

On pages 3-4 of the outstanding office action, Claims 8-11 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Steffen. Applicant respectfully traverses this rejection on the grounds that independent Claim 8, as presently amended, is neither anticipated by nor obvious over Steffen.

Amended Claim 8 defines die bond pads and wire bond pads adapted to be mounted on a motherboard. Support for this limitation is found in the specification at page 15, lines 1-3, for example. Since the Steffen reference relates to the manufacture of a "chip card," Steffen fails to teach or suggest the invention defined by Claim 8, as noted during the interview. *See* Interview Summary. Thus, independent Claim 8 and dependent Claims 9-10 are believed to patentably distinguish over Steffen.

On pages 5 and 6 of the outstanding office action, Claims 11-14 were rejected under 35 USC § 103(a) as being unpatentable over Fjelstad. Applicant respectfully traverse this rejection on the grounds that Claim 11, as presently amended, defines an invention, which as a whole, is neither anticipated by nor obvious over Fjelstad.

Claim 11 defines the steps of “fastening the back of the discrete semiconductor elements onto an electrically conductive metal sheet and connecting electrically an electrode of each discrete semiconductor element to a specified position of the metal sheet,” and also defines the step of “cutting into the metal sheet from the back to turn the metal sheet, on which the discrete semiconductor elements are fastened, into die bond pads and wire bond pads.” It is first noted that the Fjelstad discloses the use of pad regions 410 and a central conductive region 415 that are selectively electroplated onto a sacrificial sheet 400. Column 8, lines 12-17; figures 7A – 7G. Fjelstad then employs an etchant to etch the top of the sacrificial sheet between the electroplated portions, as shown in Figure 7C. Next, the electroplated portions are electrically connected to a chip 420, as shown in Figure 7D, and lastly, the bottom of the sacrificial layer is etched away to electrically isolate the different portions of the package. Column 8, lines 38-60.

Thus, it can be readily appreciated that there are major differences between amended Claim 11 and the process disclosed by Fjelstad. First, the pads 410 and 415 of Fjelstad are not separated by cutting, as claimed. Instead, Fjelstad’s pads are selectively electroplated. Second, the chip 410 of Fjelstad is not fastened and electrically connected to a metal sheet, rather, the pads 410 and 415 are already separated when the chip 420 is connected, as shown in Figures 7C and 7D. Third, Fjelstad electrically isolates the various components of the package as shown in Figures 7F and 7G by etching into the sacrificial layer 400. Fjelstad does not etch into the pads 410 and 415. On the other hand, Claim 11 defines cutting into the metal sheet from the back to turn the metal sheet, on which the discrete semiconductor elements are fastened, into die bond pads and wire bond pads. Fjelstad does not appear to do any cutting, etching, or further processing of the pads 410 and 415 after the chip 420 is fastened and electrically connected to the pads 410 and 415. Accordingly, Fjelstad is not believed to teach or suggest the invention of Claim 11. Therefore, applicant respectfully

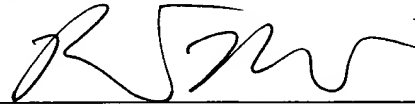
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submits that Claim 11 and dependent Claims 12-14 patentably distinguish over the Fjelstad reference.

In view of the foregoing discussion, no further issues are believed to be outstanding in the present application. Therefore, applicant respectfully requests that the present application be allowed and be passed to issue.

Respectfully submitted,

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